孙大鹏

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概述

- 有国家重点实验室3年模拟集成电路设计经验
- 有成功流片和测试经验 (工艺: GlobalFoundries 0.18 微米)
- 硬件技能: 熟悉 Cadence 设计工具和 Altium designer (Protel) 设计工具
- 编程技能:熟悉 Matlab 编程
- 英语: 通过 CET-6, 良好的听说读写能力
- 有很好的团队合作能力,自觉主动完成工作
- 喜欢游泳和羽毛球

教育经历

1. 澳门大学, 07/2018

理学硕士(学术型), 电气与计算机工程 (GPA: 3.58/4)

导师: 罗文基教授和麦沛然教授

论文题目: "基于分段重组电流工艺补偿的 CMOS 温度传感器"

2. 南通大学, 06/2015

工学学士, 电子信息工程 (GPA: 83/100)

研究课题

1. 2017-2018, 基于双极型晶体管(BJT)工艺补偿的CMOS温度传感器

澳门科学基金会项目

- 基于双极性晶体管分段工艺补偿方法,提出了一种低成本的 CMOS 温度传感器,同时提高了不同工艺 批次的温度传感器的传感精度 (±1.5°C)。(Electronics Letters '18)
- 2. 2016-2017, BJT 分段工艺误差补偿技巧

澳门科学基金会项目

■ 利用 BJT 自身的重组电流,提出了在一个大的温度范围内的 BJT 分段工艺补偿方法,把工艺误差减小超过一倍。(ISCAS '17)

组织经历

 06/2017 – Now
 国际电子电气工程师协会 学生会员

 2016 – 2017
 澳门大学科技学院研究生会 主席

荣誉奖励

07/2018 **优秀硕士毕业生**,澳门大学 09/2015 – 07/2018 研究生奖学金,澳门大学

06/2015 **优秀本科毕业论文**(前 5%), 南通大学

2011 – 2012 国家励志奖学金,中国教育部 2011 – 2012 校二等奖学金,南通大学

发表论文

- 1. **Dapeng Sun**, Tan-Tan Zhang, Man-Kay Law, Pui-In Mak and Rui P. Martins, "<u>Process compensated bipolar junction transistor-based CMOS temperature sensor with a ±1.5 °C (3σ) batch-to-batch inaccuracy</u>", *IET Electronics Letters*, Sep. 2018. (**SCI**)
- 2. **Dapeng Sun**, Man-Kay Law, Bo Wang, Pui-In Mak and Rui P. Martins, "<u>Piecewise BJT Process Spread Compensation Exploiting Base Recombination Current</u>", *IEEE International Symposium on Circuits and Systems* (*ISCAS*), Sep. 2017. (**EI**)

Dapeng Sun, Daniel

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Summary

- 3 years of analog IC design experience at the <u>State Key Laboratory</u>.
- Successful tape-out and chip-testing experience (GlobalFoundries 0.18-μm).
- Hardware: Familiar with Cadence IC design tools, Altium designer (Protel).
- Programming: Familiar with Matlab.
- English proficiency: CET-6, proficient in reading, writing and speaking.
- Good team work spirit and highly self-motivated.
- Hobbies: Swimming, Badminton.

Education

1. M.Sc. in Electrical and Computer Engineering, University of Macau, 07/2018.

GPA: 3.58/4

Advisor: Prof. Man-Kay Law and Prof. Pui-In Mak.

Thesis: "Process Compensated CMOS Temperature Sensor Exploiting Piecewise Base Recombination Current."

2. B.Eng. in Electronic and Information Engineering, Nantong University, 06/2015.

GPA: 83/100

Research Projects

- 1. 2017 2018, Process Compensated Bipolar Junction Transistor (BJT) Based CMOS Temperature Sensor
 - Proposed a low-cost solution for CMOS temperature sensor design based on the proposed piecewise BJT process compensation method, to improve the temperature sensing accuracy over the different batches (±1.5 °C). (Electronics Letters '18)
- 2. 2016 2017, Piecewise BJT Process Compensation Technique
 - Proposed a piecewise BJT process compensation method over a wide temperature range by exploiting the recombination current from the BJT itself, to reduce the process variations. (ISCAS '17)

Leaderships

05/2017 - Now	IEEE Graduate Student Member, Institute of Electrical and Electronic Engineers
2016 - 2017	President of Faculty of Science and Technology Postgraduate Students' Association,
	University of Macau (FST-UMPA)

Honors and Awards

07/2018	Excellent Graduate Student, University of Macau
09/2015 - 07/2018	Graduate Student Fellowship, University of Macau
06/2015	Excellent Undergraduate Graduation Thesis (Top 5%), Nantong University
2011 - 2012	National Scholarship for Encouragement, China Ministry of Education
2011 - 2012	The Second Prize Scholarship, Nantong University

Research Publications

- 1. **Dapeng Sun**, Tan-Tan Zhang, Man-Kay Law, Pui-In Mak and Rui P. Martins, "<u>Process compensated bipolar junction transistor-based CMOS temperature sensor with a ±1.5 °C (3σ) batch-to-batch inaccuracy</u>", *IET Electronics Letters*, Sep. 2018. (**SCI**)
- 2. **Dapeng Sun**, Man-Kay Law, Bo Wang, Pui-In Mak and Rui P. Martins, "<u>Piecewise BJT Process Spread Compensation Exploiting Base Recombination Current</u>", *IEEE International Symposium on Circuits and Systems* (*ISCAS*), Sep. 2017. (**EI**)